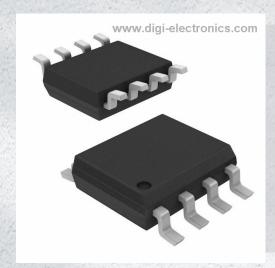


FDS5690-NBBM009A Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number FDS5690-NBBM009A-DG

Manufacturer onsemi

Manufacturer Product Number FDS5690-NBBM009A

Description MOSFET N-CH 60V 7A 8SOIC

Detailed Description N-Channel 60 V 7A (Ta) Surface Mount 8-SOIC



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



Purchase and inquiry

| Manufacturer Product Number: | Manufacturer: |
|---------------------------------|---|
| FDS5690-NBBM009A | onsemi |
| Series: | Product Status: |
| | Obsolete |
| FET Type: | Technology: |
| N-Channel | MOSFET (Metal Oxide) |
| Drain to Source Voltage (Vdss): | Current - Continuous Drain (Id) @ 25°C: |
| 60 V | 7A (Ta) |
| Rds On (Max) @ Id, Vgs: | Vgs(th) (Max) @ ld: |
| 28mOhm @ 7A, 10V | 4V @ 250μA |
| Gate Charge (Qg) (Max) @ Vgs: | Input Capacitance (Ciss) (Max) @ Vds: |
| 32 nC @ 10 V | 1107 pF @ 30 V |
| FET Feature: | Mounting Type: |
| | Surface Mount |
| Supplier Device Package: | Package / Case: |
| 8-SOIC | 8-SOIC (0.154", 3.90mm Width) |
| Base Product Number: | |
| FDS56 | |

Environmental & Export classification

8541.29.0095

| RoHS Status: | Moisture Sensitivity Level (MSL): |
|------------------|-----------------------------------|
| ROHS3 Compliant | 1 (Unlimited) |
| REACH Status: | ECCN: |
| REACH Unaffected | EAR99 |
| HTSUS: | |

ON Semiconductor

Is Now



To learn more about onsemi™, please visit our website at www.onsemi.com

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,



ON Semiconductor®

FDS5690

60V N-Channel PowerTrench MOSFET

General Description

This N-Channel MOSFET is produced using $\frac{ON}{A} \cdot 7 \text{ A}$, 60 V. $\frac{ON}{A} = 0.028 \Omega \cdot \text{W}$ $\frac{ON}{A} = 10 \text{ V}$ Semiconductor's advanced PowerTrench process that has been especially tailored to minimize on-state resistance and yet maintain superior switching performance.

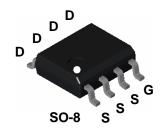
These devices are well suited for low voltage and battery • Fast switching speed. powered applications where low in-line power loss and fast switching are required.

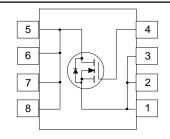
Applications

- DC/DC converter
- Motor drives

Features

- $\rm R_{DS(on)}$ = 0.033 Ω @ $\rm V_{GS}$ = 6 V.
- Low gate charge (23nC typical).
- High performance trench technology for extremely
- High power and current handling capability.





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

| Symbol | Parameter | | Ratings | Units | |
|-----------------------------------|--|-----------|-------------|-------|--|
| V _{DSS} | Drain-Source Voltage | | 60 | V | |
| V _{GSS} | Gate-Source Voltage | | <u>+</u> 20 | V | |
| I _D | Drain Current - Continuous | (Note 1a) | 7 | А | |
| | - Pulsed | | 50 | | |
| P _D | Power Dissipation for Single Operation | (Note 1a) | 2.5 | W | |
| | (Note 1b) | 1.2 | | | |
| | | (Note 1c) | 1 | | |
| T _J , T _{stg} | Operating and Storage Junction Temperature Range | | -55 to +150 | °C | |

Thermal Characteristics

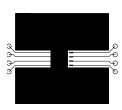
| $R_{\theta^{JA}}$ | Thermal Resistance, Junction-to-Ambient | (Note 1a) | 50 | °C/W |
|-------------------|---|-----------|----|------|
| $R_{\theta^{JC}}$ | Thermal Resistance, Junction-to-Case | (Note 1) | 25 | °C/W |

Package Outlines and Ordering Information

| Device Marking | Device | Reel Size | Tape Width | Quantity |
|----------------|---------|-----------|------------|------------|
| FDS5690 | FDS5690 | 13" | 12mm | 2500 units |

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|---------------------|---|---|-----|-------------------------|-------------------------|-------|
| Off Char | acteristics | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$ | 60 | | | V |
| ABVDSS | Breakdown Voltage Temperature Coefficient | I_D = 250 μ A, Referenced to 25°C | | 57 | | mV/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 48 V, V _{GS} = 0 V | | | 1 | μA |
| I _{GSSF} | Gate-Body Leakage Current, Forward | V _{GS} = 20 V, V _{DS} = 0 V | | | 100 | nA |
| I _{GSSR} | Gate-Body Leakage Current, Reverse | V _{GS} = -20 V, V _{DS} = 0 V | | | -100 | nA |
| On Char | acteristics (Note 2) | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | 2 | 2.5 | 4 | V |
| ΔVGS(th) ΔTJ | Gate Threshold Voltage Temperature Coefficient | $I_D = 250 \mu A$, Referenced to 25°C | | -5.9 | | mV/∘C |
| R _{DS(on)} | Static Drain-Source On-Resistance | $V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}, T_J = 125 ^{\circ}\text{C}$ $V_{GS} = 6 \text{ V}, I_D = 6.5 \text{ A}$ | | 0.022 0.037 0.025 | 0.028 0.050 0.033 | Ω |
| I _{D(on)} | On-State Drain Current | V _{GS} = 10 V, V _{DS} = 5 V | 25 | | | Α |
| g _{FS} | Forward Transconductance | $V_{DS} = 10 \text{ V}, I_{D} = 7 \text{ A}$ | | 24 | | S |
| Dvnamio | : Characteristics | | | | | |
| C _{iss} | Input Capacitance | $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$ | | 1107 | | pF |
| Coss | Output Capacitance | f = 1.0 MHz | | 149 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 72 | | pF |
| Switchin | g Characteristics (Note 2) | | | | | |
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD} = 30 \text{ V}, I_{D} = 1 \text{ A}, \\ V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$ | | 10 | 18 | ns |
| t _r | Turn-On Rise Time | | | 9 | 18 | ns |
| t _{d(off)} | Turn-Off Delay Time | | | 24 | 39 | ns |
| t _f | Turn-Off Fall Time | | | 10 | 18 | ns |
| $\overline{Q_g}$ | Total Gate Charge | $V_{DS} = 30 \text{ V}, I_{D} = 7 \text{ A},$ $V_{GS} = 10 \text{ V},$ | | 23 | 32 | nC |
| $\overline{Q_gs}$ | Gate-Source Charge | | | 4 | | nC |
| Q_{gd} | Gate-Drain Charge | | | 6.8 | | nC |
| Drain-So | ource Diode Characteristics and | d Maximum Ratings | | | | |
| I _S | Maximum Continuous Drain-Source Diode Forward Current | | | | 2.1 | Α |
| $\overline{V_{SD}}$ | Drain-Source Diode Forward Voltage | V _{GS} = 0 V, I _S = 2.1 A (Note 2) | | 0.75 | 1.2 | V |

1. R_{BJA} is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.







a) 50° C/W when mounted on a 0.5 in² pad of 2 oz. copper.

b) 105° C/W when mounted on a 0.02 in² pad of 2 oz. copper.

c) 125° C/W when mounted on a 0.003 in² pad of 2 oz. copper.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%

Typical Characteristics

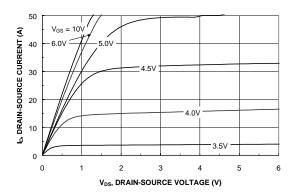


Figure 1. On-Region Characteristics.

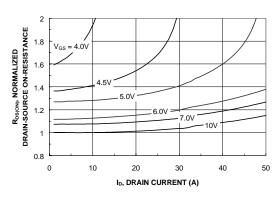


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

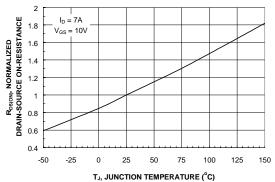


Figure 3. On-Resistance Variation with Temperature.

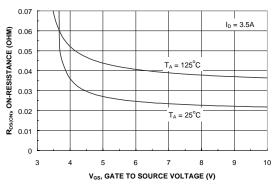


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

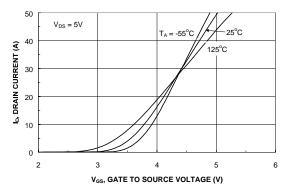


Figure 5. Transfer Characteristics.

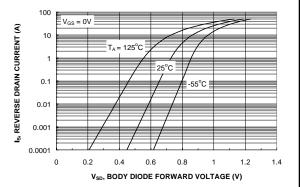
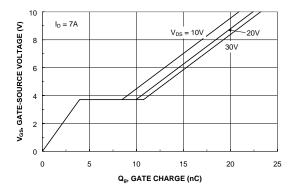


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)



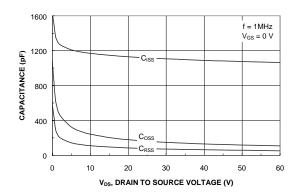
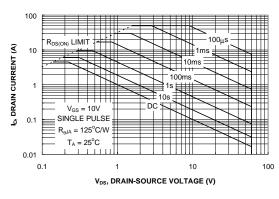


Figure 7. Gate Charge Characteristics.

Figure 8. Capacitance Characteristics.



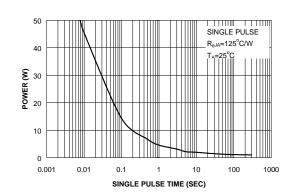


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

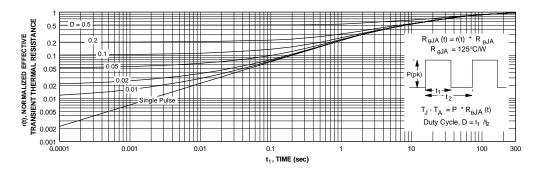


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient themal response will change depending on the circuit board design.

ON Semiconductor and III) are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages.

Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative



OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we striciy control the quality of products and services. Welcome your RFQ to Email: Info@DiGi-Electronics.com

















Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com